ADAM TECH

Adam Technologies, Inc.

CARD EDGE CONNECTORS

.100" X .200" [2.54 X 5.08] CENTERLINE CE SERIES

INTRODUCTION:

Adam Tech CE Series Card Edge Connectors are precision engineered PCB mount connectors developed to mate with the plated fingers of a printed circuit daughter board. Their bifurcated, cantilever contacts are set in a dual readout configuration and they offer a reliable connection for a wide range of PCB thicknesses. Adam Tech's sturdy solder tails with tapers allow easy insertion and rugged durability.

FEATURES:

.100" x .200" centerlines Selectively gold plated contacts Wide selection of positions Compatible with a wide range of PCB thicknesses

MATING PC BOARDS:

All printed circuit boards with a thickness of .055" to .075"

SPECIFICATIONS:

Material:

Standard insulator: PBT, 30% glass reinforced, rated UL94V-0 Optional Hi-Temp insulator: Nylon 6T, rated UL94V-0 Insulator Color: Black Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 μin Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 250V AC max. Current rating: 3 Amps max. Contact resistance: 30 m Ω max. initial Insulation resistance: 3000 M Ω min. Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 10 oz max. Withdrawal force: 3 oz min

Temperature Rating:

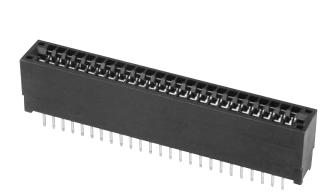
Operating temperature: -40°C to +105°C Soldering process temperature: Standard insulator: 235°C Hi-Temp insulator: 260°C

PACKAGING: Anti-ESD plastic trays

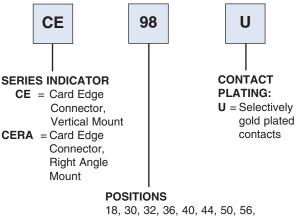
SAFETY AGENCY APPROVALS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596





ORDERING INFORMATION



18, 30, 32, 36, 40, 44, 50, 5 60, 62, 80, 98, 100

OPTIONS:

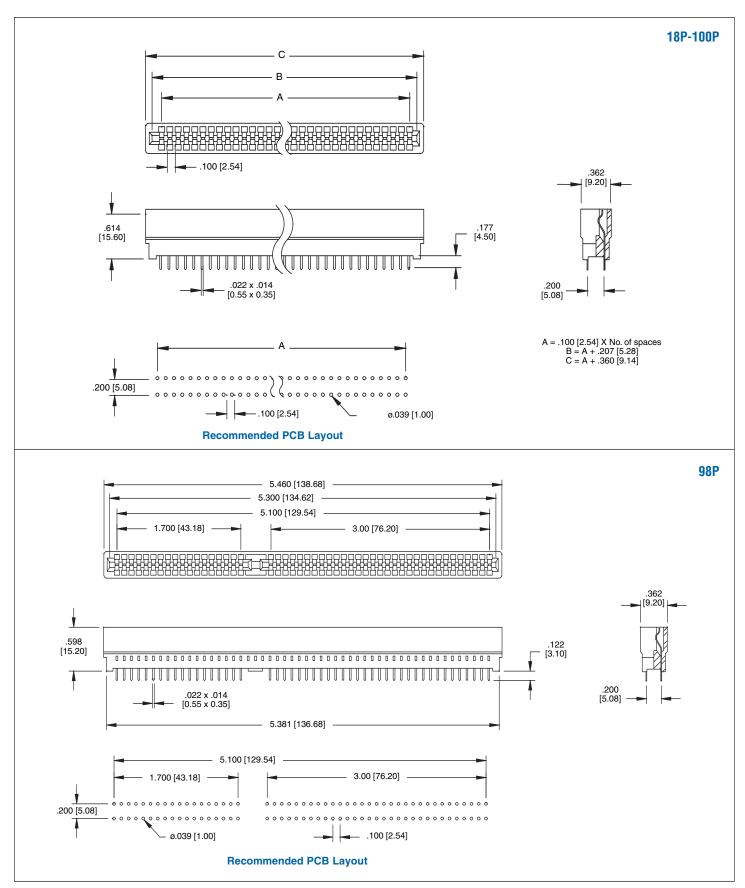
Add designator(s) to end of part number 30 = 30 μin gold plating in contact area HT = Hi-Temp insulator for Hi-Temp soldering processes up to 260°C



CARD EDGE CONNECTORS

.100" X .200" [2.54 X 5.08] CENTERLINE

CE SERIES



ADAM TECH

Adam Technologies, Inc.

HIGH DENSITY CARD EDGE .050" [1.27] VESA MICRO CHANNEL ARCHITECTURE (MCA) HMCA SERIES

INTRODUCTION:

Adam Tech HMCA Series Card Edge Connectors include Standard and Express versions designed for PCB's in Peripheral Component Interconnect (PCI) applications. Each is manufactured in a four row, high density package which is completely compatible to industry standards and has specially engineered contacts which provide a very short electrical path between boards. Adam Tech card edge connectors are designed for high performance with solid board pegs and precision located, selectively gold plated contacts which are ideal in high speed, increased bandwidth applications

FEATURES:

PCI and PCI Express Versions High density compact designs Industry standard PCI compatible Special contact design reduces electrical path Selectively plated contacts Open bottom for after solder cleaning

MATING PC BOARDS:

All .050" centerline printed circuit board pads with a thickness of .062" to .072"

SPECIFICATIONS: Material:

Standard insulator: PPS, 30% glass reinforced, rated UL94V-0 Optional Hi-Temp insulator: Nylon 6T, rated UL94V-0 Insulator Color: Dark Brown (White 120 pos.) Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 $\mu\text{in}\,$ Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 125V AC max.

Current rating: 1 Amp max. Contact resistance: 30 m Ω max. initial

Insulation resistance: 1000 M Ω min.

Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 7 oz max. Withdrawal force: 0.9 oz min

Temperature Rating:

Operating temperature: -55°C to +105°C Soldering process temperature: Standard insulator: 235°C

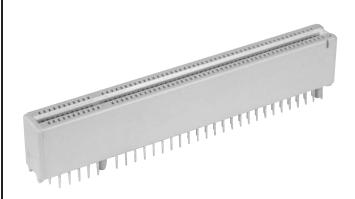
Hi-Temp insulator: 260°C

PACKAGING: Anti-ESD plastic trays

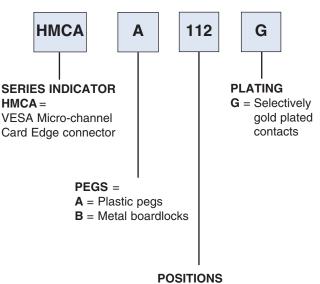
SAFETY AGENCY APPROVALS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596





ORDERING INFORMATION



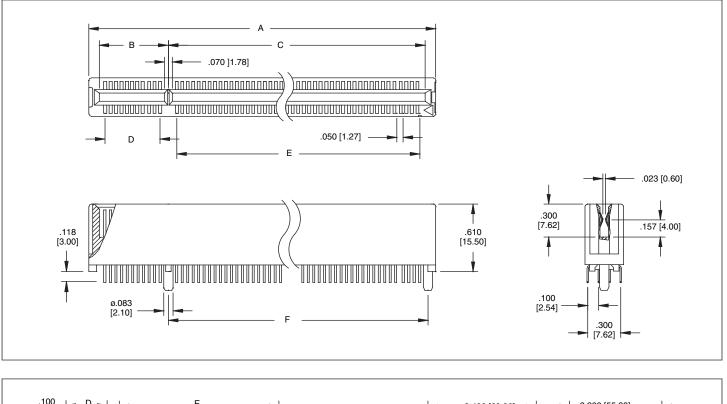
112, 120, 132, 182, 184, 194

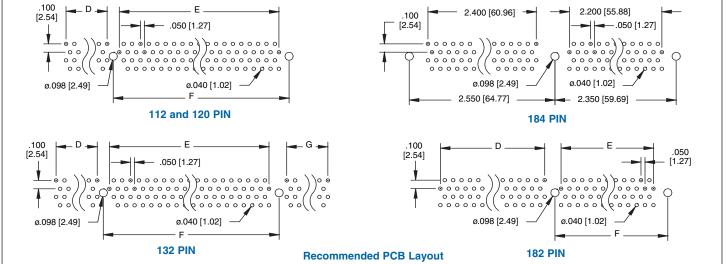
OPTIONS

Add designator(s) to end of part number **30** = 30 μin gold plating in contact area **HT** = Hi-Temp insulator for Hi-Temp soldering processes up to 260°C



HIGH DENSITY CARD EDGE .050" [1.27] VESA MICRO CHANNEL ARCHITECTURE (MCA) HMCA SERIES





Unit: Inch [mm]

Part No. & Positions	Dimensions						
	А	В	с	D	E	F	G
HMCA-112-G	3.140 [79.76]	0.625 [15.88]	2.325 [59.06]	0.500 [12.70]	2.200 [55.88]	2.232 [56.69]	—
HMCA-120-G	3.340 [84.84]	0.625 [15.88]	2.525 [64.14]	0.500 [12.70]	2.400 [60.96]	2.550 [64.77]	—
HMCA-132-G	3.740 [95.00]	0.625 [15.88]	2.925 [74.30]	1.834 [46.60]	2.200 [55.88]	2.350 [59.69]	0.450 [11.43]
HMCA-182-G	4.890 [124.21]	2.175 [55.25]	2.525 [64.14]	2.050 [52.07]	2.050 [52.07]	2.550 [64.77]	—
HMCA-194-G	5.290 [134.37]	2.175 [55.25]	2.925 [74.30]	2.050 [52.07]	2.200 [55.88]	2.350 [55.88]	0.450 [11.43]

ADAM TECH

HIGH DENSITY CARD EDGE

Adam Technologies, Inc.

.050" [1.27] CENTERLINE EISA CONNECTOR HDCE SERIES

INTRODUCTION:

Adam Tech HDCE Series EISA (Extended Industry Standard Architecture) Card Edge Connectors are .050" pitch 188 position dual level contact connectors specifically designed to mate with AT, XT and PC expansion cards. Our precision formed High Reliability contact system is contained within a Hi-Temp PPS body which features a close tolerance polarizing slot and card edge lead-in area for superior mating.

FEATURES:

High density .050" Centerlines Compatible with PC, XT & AT Durable Long Life cycle contacts High Pressure Contacts for Low Level Circuits

MATING PC BOARDS:

All .050" centerline printed circuit board pads with a thickness of .062" to .072"

SPECIFICATIONS:

Material:

Standard insulator: PPS, 30% glass reinforced, rated UL94V-0 Optional Hi-Temp insulator: Nylon 6T, rated UL94V-0 Insulator Color: Dark Brown (Black optional) Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 μin Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 125V AC max. Current rating: 3 Amps max. Contact resistance: 20 m Ω max. initial Insulation resistance: 1000 M Ω min. Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 7 oz max. Withdrawal force: 0.9 oz min

Temperature Rating:

Operating temperature: -55°C to +105°C Soldering process temperature: Standard insulator: 235°C Hi-Temp insulator: 260°C

PACKAGING: Anti-ESD plastic trays

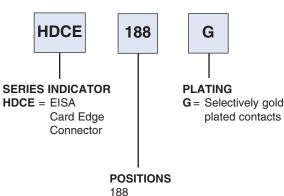
APPROVALS AND CERTIFICATIONS:

UL Recognized File No. E224053 CSA Certified File No. LR1578596





ORDERING INFORMATION





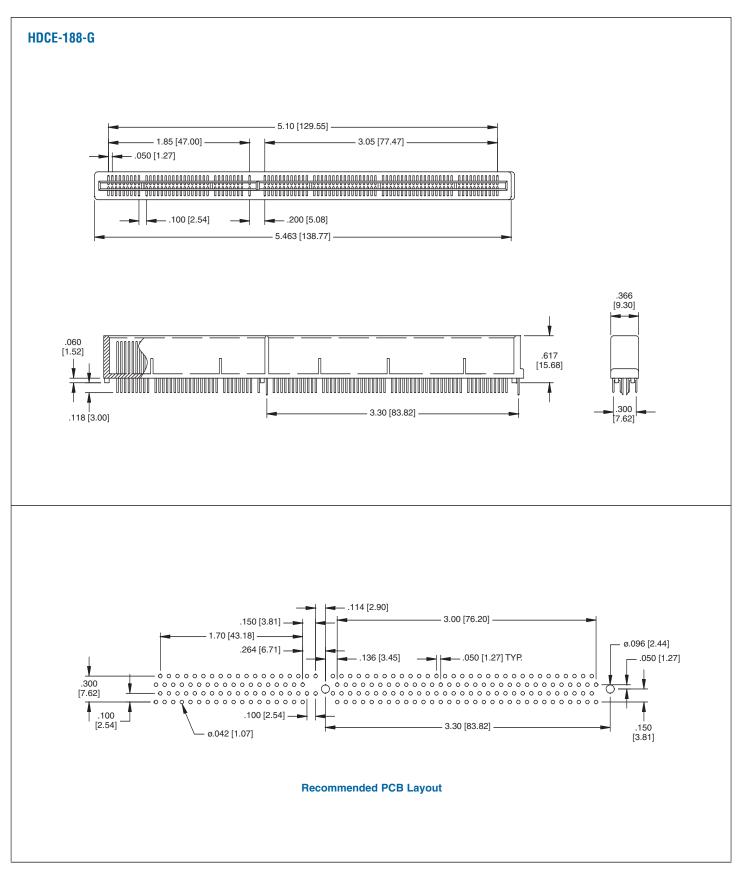
Add designator(s) to end of part number
30 = 30 μin gold plating in contact area
BK = Black color insulation
HT = Hi-Temp insulator for Hi-Temp soldering processes up to 260°C



HIGH DENSITY CARD EDGE

.050" [1.27] CENTERLINE EISA CONNECTOR

HDCE SERIES



ADAM TECH Adam Technologies, Inc.

PCI & MINI PCI EXPRESS 1.00mm & 0.8mm CARD EDGE CONNECTOR

PCIE SERIES

INTRODUCTION:

Adam Tech's wide range of PCI & Mini PCI Express connectors provide a low cost, highly scalable, general-purpose serial I/O interconnect that provides a unifying standard for a number of I/O solutions within one platform. They are typically used in high-speed serial link technology applications similar to that found in Gigabit1 Ethernet, Serial ATA (SATA), and Serial-Attached SCSI (SAS). The 36P version supports a single PCI express lane and can be used to replace standard PCI connectors. Our higher bandwidth 4 & 8 lane versions are ideal to use in many server applications.

FEATURES:

Durable Long Life cycle contacts High Pressure Contacts for Low Level Circuits Hot plug and hot swap enabled Rated to run at up to 2.5Gbps Supports 2.5Gbps data transfer and scalable for future band width increases. Available in x1, x4, x8, and x16 configurations Coexists with standard PCI

MATING PC BOARDS:

All printed circuit boards with a thickness of .062" to .072"

SPECIFICATIONS:

Material:

Standard insulator: PPS, 30% glass reinforced, rated UL94V-0 Optional Hi-Temp insulator: Nylon 6T, rated UL94V-0 Insulator Color: Dark Brown Contacts: Phosphor Bronze

Contact Plating:

Gold Flash (30 µin Optional) over Nickel underplate on contact area, tin over copper underplate on tails.

Electrical:

Operating voltage: 125V AC max. Current rating: 3 Amps max. Contact resistance: 20 m Ω max. initial Insulation resistance: 1000 M Ω min. Dielectric withstanding voltage: 500V AC for 1 minute

Mechanical:

Insertion force: 7 oz max. Withdrawal force: 0.9 oz min

Temperature Rating:

Operating temperature: -55°C to +105°C Soldering process temperature: Standard insulator: 235°C Hi-Temp insulator: 260°C

PACKAGING:

Anti-ESD plastic trays

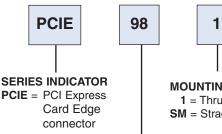
APPROVALS AND CERTIFICATIONS: UL Recognized File No. E224053 CSA Certified File No. LR1578596







ORDERING INFORMATION PCI EXPRESS



MOUNTING 1 = Thru-Hole PCB Tails SM = Straddle Mount

POSITIONS MPCI = 36, 64, 98, 164

ORDERING INFORMATION MINI PCI EXPRESS

See pg. 177 for Available Types

OPTIONS:

Add designator(s) to end of part number

- 30 = 30 µin gold plating in contact area
- HT = Hi-Temp insulator for Hi-Temp soldering processes up to 260°C
- **LL** = Latch option left side

LR = Latch option right side

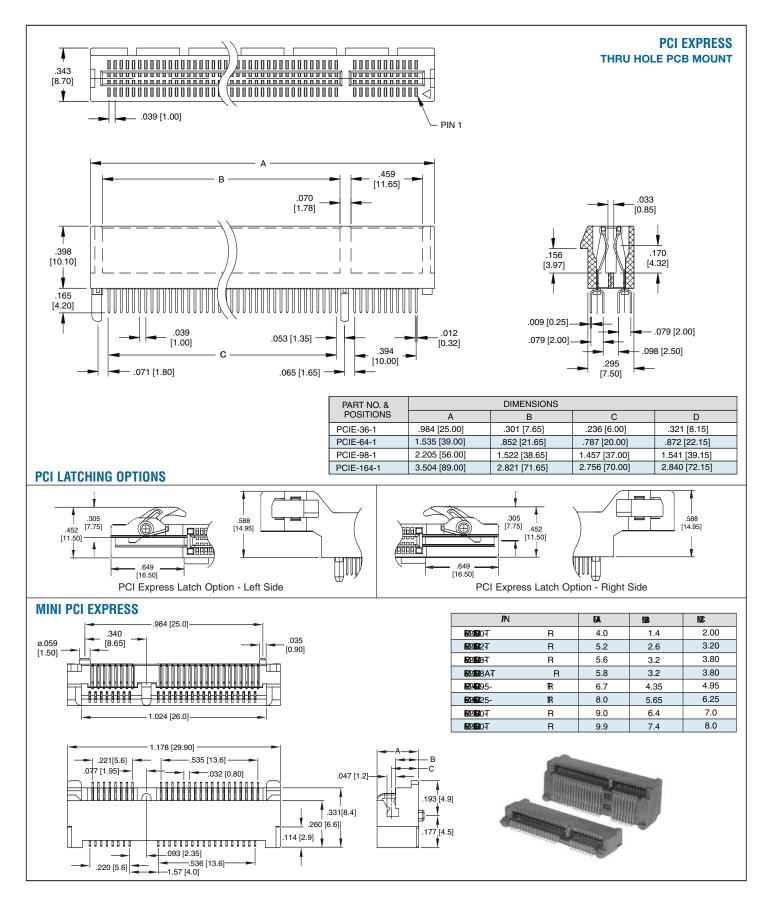
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PCI & MINI PCI EXPRESS

1.00mm & 0.8mm CARD EDGE CONNECTOR

PCIE SERIES





PCI & MINI PCI EXPRESS

1.00mm & 0.8mm CARD EDGE CONNECTOR

PCIE SERIES

